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(54) LEAD FRAME

(57) Abstract:

PURPOSE: To provide a lead frame in which an island is not eccentrically deviated by solving a problem in which the island is eccentrically deviated in the case of resin-sealing and the island is exposed out of a mold.

CONSTITUTION: A protrusion 20 for generating a force for floating an island 18 upon reception of flow A of resin is provided on the island 18 for placing a semiconductor chip.

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